

## Product Change Notification - KSRA-30MKCM076 (Printer Friendly)

**Date:**

12 Feb 2018

**Product Category:**
**Notification subject:**

CCB 3269 Initial Notice: Qualification of 8600 die attach and G700LTD mold compound for selected products available in 8L TDFN package at NSEB assembly site.

**Notification text:**
**PCN Status:**

Initial notification

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of 8600 die attach and G700LTD mold compound for selected products available in 8L TDFN package at NSEB assembly site.

**Pre Change:**

Using 8200T die attach material and G770HCD molding compound material

**Post Change:**

Using 8200T or 8600 die attach material and G770HCD or G700LTD molding compound material

**Pre and Post Change Summary:**

	Pre Change	Post Change	
<b>Assembly Site</b>	UTAC Thai Limited LTD. / NSEB	UTAC Thai Limited LTD. / NSEB	UTAC Thai Limited LTD. / NSEB
<b>Wire material</b>	Au wire	Au wire	Au wire
<b>Die attach material</b>	8200T	8200T	8600
<b>Molding compound material</b>	G770HCD	G770HCD	G700LTD
<b>Lead frame material</b>	C194	C194	C194

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**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve manufacturability by qualifying G700LTD mold compound and 8600 die attach material.

**Change Implementation Status:**

In Progress

**Estimated Qualification Completion Date:**

May 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

Workweek	February 2018					→	May 2018				
	05	06	07	08	09		18	19	20	21	22
Initial PCN Issue Date			X								
Qual Report Availability							X				
Final PCN Issue Date							X				

**Method to Identify Change:**

Traceability code

**Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan

**Revision History:****February 12, 2018:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**[PCN\\_KSRA-30MKCM076\\_Affected CPN.pdf](#)[PCN\\_KSRA-30MKCM076\\_Qual Plan.pdf](#)[PCN\\_KSRA-30MKCM076\\_Affected CPN.xlsx](#)

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